



Material Content Data Sheet



Sales Product Name		TLE5205-2GP		Issued		28. August 2013		
MA#		MA000543914						
Package		PG-DSO-20-37		Weight*		1.15 g		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [g]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.000	0.00		0	3600
leadframe	inorganic material	phosphorus	7723-14-0	0.000	0.00		0	
	non noble metal	zinc	7440-66-6	0.000	0.00		0	
	non noble metal	iron	7439-89-6	0.000	0.00		0	
wire	non noble metal	copper	7440-50-8	0.000	0.00		0	3600
	noble metal	gold	7440-57-5	0.000	0.00		0	3600
	encapsulation	organic material	carbon black	1333-86-4	0.000	0.00		0
encapsulation	plastics	epoxy resin	-	0.000	0.00		0	
	inorganic material	silicondioxide	60676-86-0	0.000	0.00		0	3600
leadfinish	non noble metal	tin	7440-31-5	0.000	0.00		0	3600
solder	noble metal	silver	7440-22-4	0.000	0.00		0	
	non noble metal	tin	7440-31-5	0.000	0.00		0	
	non noble metal	lead	7439-92-1	0.000	0.00		0	3600
*deviation	< 10%		Sum in total:			0,00		21601

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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